

05/04/03

ABSTRACT of the Disclosure

A method including in a wafer processing environment, introducing a liquid via a carrier gas, and separate from the liquid, introducing a first gas comprising ozone and a legacy amount of oxygen and a second gas comprising an effective amount of oxygen to modify a process operation. A system including a chamber, a liquid source, a first gas source, and a second gas source, a controller configured to control the introduction into the chamber of a liquid from the liquid source, a first gas comprising ozone and a legacy amount of oxygen from the first gas source, a second gas comprising oxygen from the second gas source, and a memory coupled to the controller comprising a machine-readable medium having a program embodied therein for controlling the second gas source to introduce an effective amount of oxygen into the chamber to modify a process operation.

10025442-121801